

MOSFET - Power, Single N-Channel, SUPERFET®, **FAST, TO247-4L** 600 V, 61 mΩ, 41 A

NTH4LN061N60S5H

Description

The SUPERFET V MOSFET FAST series helps maximize system efficiency by the extremely low switching losses in hard switching application.

Features

- 100% Avalanche Tested
- Pb-Free, Halogen Free / BFR Free and RoHS Compliant

Applications

- Telecom / Server Power Supplies
- EV Charger / UPS / Solar / Industrial Power Supplies

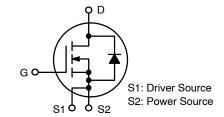
MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parameter	Symbol	Value	Unit	
Drain-to-Source Voltage		V_{DSS}	600	V
Gate-to-Source Voltage	DC	V_{GS}	±30	V
	AC (f > 1 Hz)		±30	
Continuous Drain Current	T _C = 25°C	I _D	41	Α
	T _C = 100°C		25	
Power Dissipation	T _C = 25°C	P_{D}	250	W
Pulsed Drain Current (Note 1)	T _C = 25°C	I _{DM}	144	Α
Pulsed Source Current (Body Diode) (Note 1)		I _{SM}	144	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to +150	°C
Source Current (Body Diode)		I _S	41	Α
Single Pulse Avalanche Energy	$I_L = 6.7 \text{ A},$ $R_G = 25 \Omega$	E _{AS}	376	mJ
Avalanche Current		I _{AS}	6.7	Α
Repetitive Avalanche Energy (Note 1)		E _{AR}	2.5	mJ
MOSFET dv/dt		dv/dt	120	V/ns
Peak Diode Recovery dv/dt (Note 2)			20	
Lead Temperature for Soldering Purposes (1/8" from case for 10 seconds)		T_L	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. Repetitive rating: pulse-width limited by maximum junction temperature.
- 2. $I_{SD} \le 20.5 \text{ A}$, $di/dt \le 200 \text{ A}/\mu\text{s}$, $V_{DD} \le 400 \text{ V}$, starting $T_J = 25^{\circ}\text{C}$.

V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX	
600 V	61 mΩ @ 10 V	41 A	



N-CHANNEL MOSFET



MARKING DIAGRAM



NTH4LN061N60S5H = Specific Device Code

= Assembly Location

= Year WW = Work Week = Lot Traceability

ORDERING INFORMATION

Device	Package	Shipping
NTH4LN061N60S5H	TO247-4L	30 Units / Tube

THERMAL CHARACTERISTICS

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{ heta JC}$	0.5	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	40	

ELECTRICAL CHARACTERISTICS (T_{.1} = 25°C unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
OFF CHARACTERISTICS	•			<u>.</u>		
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}, T_J = 25^{\circ}\text{C}$	600	-	-	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	$\Delta V_{(BR)DSS}/ \Delta T_J$	I _D = 10 mA, Referenced to 25°C	-	630	-	mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V, V _{DS} = 600 V, T _J = 25°C	-	-	2	μΑ
Gate-to-Source Leakage Current	I _{GSS}	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	±100	nA
ON CHARACTERISTICS						-
Drain-to-Source On Resistance	R _{DS(on)}	$V_{GS} = 10 \text{ V}, I_D = 20.5 \text{ A}, T_J = 25^{\circ}\text{C}$	-	48.8	61	mΩ
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D = 4.4 \text{ mA}, T_J = 25^{\circ}\text{C}$	2.7	-	4.3	٧
Forward Transconductance	9 _{FS}	V _{DS} = 20 V, I _D = 20.5 A	-	41.7	-	S
CHARGES, CAPACITANCES & GATE RE	SISTANCE					-
Input Capacitance	C _{ISS}	$V_{DS} = 400 \text{ V}, V_{GS} = 0 \text{ V}, f = 250 \text{ kHz}$	-	4157	-	pF
Output Capacitance	C _{OSS}	1	-	60.1	-	1
Time Related Output Capacitance	C _{OSS(tr)}	I_D = Constant, V_{DS} = 0 to 400 V, V_{GS} = 0 V	-	935	-	
Energy Related Output Capacitance	C _{OSS(er)}	V _{DS} = 0 to 400 V, V _{GS} = 0 V	-	100	-	1
Total Gate Charge	Q _{G(TOT)}	V _{DD} = 400 V, I _D = 20.5 A,	-	74.2	-	nC
Gate-to-Source Charge	Q_{GS}	V _{GS} = 10 V	-	20.1	-	
Gate-to-Drain Charge	Q_{GD}		-	19.7	-	1
Gate Resistance	R_{G}	f = 1 MHz	-	0.7	-	Ω
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	t _{d(ON)}	$V_{GS} = 0/10 \text{ V}, V_{DD} = 400 \text{ V},$	-	31.9	-	ns
Rise Time	t _r	I_D = 20.5 A, R_G = 4.7 Ω	-	9.08	-	
Turn-Off Delay Time	t _{d(OFF)}	1	-	82.4	-	1
Fall Time	t _f	1	_	2.64	-	1
SOURCE-TO-DRAIN DIODE CHARACTE	RISTICS			-	•	-
Forward Diode Voltage	V _{SD}	$I_{SD} = 20.5 \text{ A}, V_{GS} = 0 \text{ V}, T_{J} = 25^{\circ}\text{C}$	-	-	1.2	V
Reverse Recovery Time	t _{RR}	$V_{GS} = 0 \text{ V}, I_{SD} = 20.5 \text{ A},$	-	416	-	ns
Reverse Recovery Charge	Q _{RR}	dl/dt =100 A/μs, V _{DD} = 400 V	_	7405	_	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

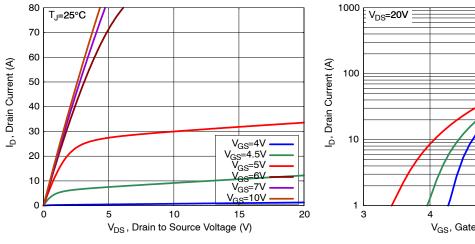


Figure 1. On-Region Characteristics

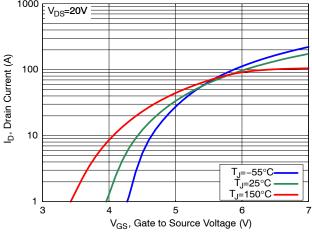


Figure 2. Transfer Characteristics

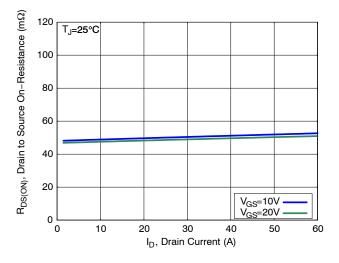


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

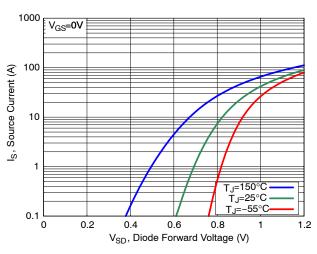


Figure 4. Diode Forward Voltage vs. Source Current

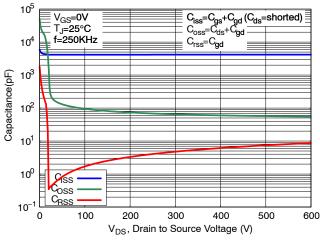


Figure 5. Capacitance Characteristics

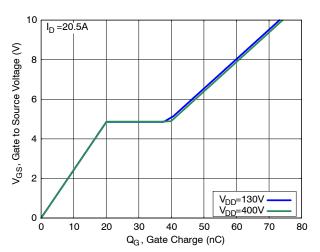


Figure 6. Gate Charge Characteristics

TYPICAL CHARACTERISTICS

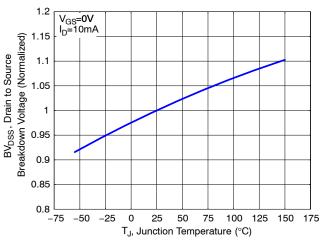


Figure 7. Breakdown Voltage Variation vs. Temperature

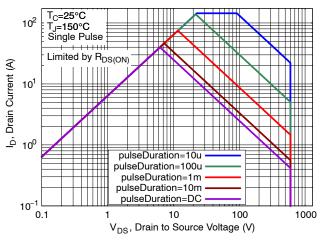


Figure 9. Maximum Safe Operating Area

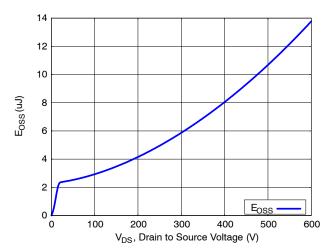


Figure 11. Eoss vs. Drain-to-Source Voltage

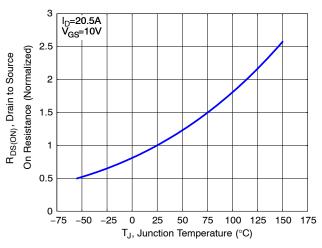


Figure 8. On–Resistance Variation vs.
Temperature

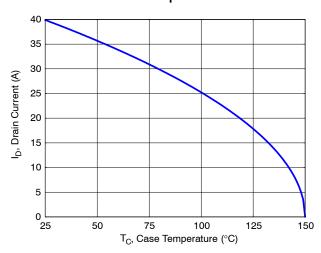


Figure 10. Maximum Drain Current vs. Case Temperature

TYPICAL CHARACTERISTICS

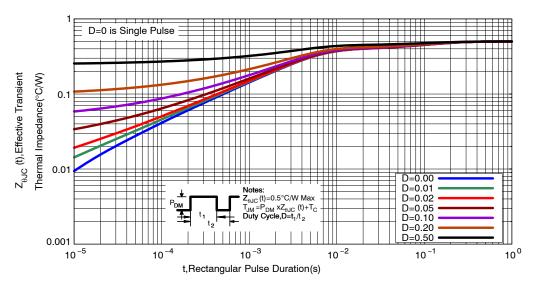
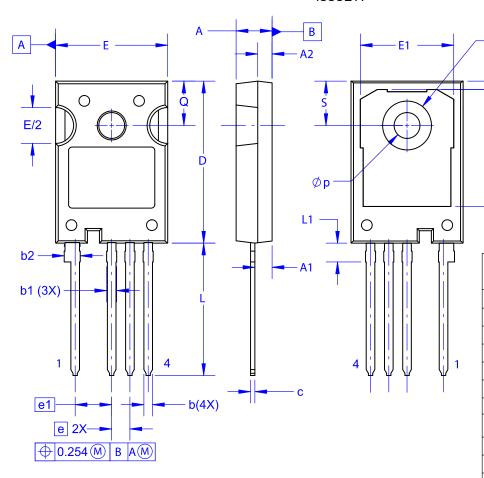


Figure 12. Transient Thermal Impedance

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PACKAGE DIMENSIONS

TO-247-4LD CASE 340CJ ISSUE A



NOTES:

- A. NO INDUSTRY STANDARD APPLIES TO THIS PACKAGE.
 B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD
 FLASH, AND TIE BAR EXTRUSIONS.
 C. ALL DIMENSIONS ARE IN MILLIMETERS.
 D. DRAWING CONFORMS TO ASME Y14.5-2009.

DIM	MIL	LIMETER	S	
DIM	MIN	NOM	MAX	
Α	4.80	5.00	5.20	
A1	2.10	2.40	2.70	
A2	1.80	2.00	2.20	
b	1.07	1.20	1.33	
b1	1.20	1.40	1.60	
b2	2.02	2.22	2.42	
С	0.50	0.60	0.70	
D	22.34	22.54	22.74	
D1	16.00	16.25	16.50	
D2	0.97	1.17	1.37	
е	2.54 BSC			
e1	5.08 BSC			
Е	15.40	15.60	15.80	
E1	12.80	13.00	13.20	
E/2	4.80	5.00	5.20	
L	18.22	18.42	18.62	
L1	2.42	2.62	2.82	
р	3.40	3.60	3.80	
p1	6.60	6.80	7.00	
Q	5.97	6.17	6.37	
S	5.97	6.17	6.37	

Ø**p1**

D1

- D2

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